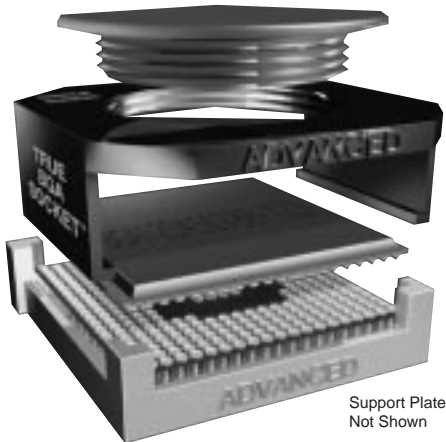


PATENTED


 Support Plate
Not Shown

True BGA Socket™ Features

- No soldering of BGA device required.
- AIC exclusive eutectic solder ball terminals offer superior processing.
- Uses same footprint as BGA device.
- Designed for production, development, programming and test applications.
- Compact design maximizes PCB real estate:
 - TSG = Device Pkg. Size + 0.216/(5.5mm)
 - TSH = Device Pkg. Size + 0.374/(9.5mm)
- Available with integral, finned heat sink or coin screw clamp assembly.
- Currently available in 1.0 and 1.27mm pitch.
- New Short Slide Clamp reduces required installation space on PCB.

Specifications

Terminals: Brass; Copper Alloy (C36000)

Terminal Support: Polyimide Film

Contacts: Beryllium Copper (C17200)

Plating: G – Gold over Nickel

Spring Material: Beryllium Copper

Clamp Assembly: Aluminum (Heat Sink/Coin Screw, Clamp, Support Plate)

Insulator Material:

Molded PPS (High Temp. Glass Filled Thermoplastic), U.L. Rated 94V-O, -60°C to 260°C (-76°F to 500°F)

Solder Ball:

Eutectic, 63Sn/37Pb, 183°C (361°F)

How It Works

Step 1

- Solder True BGA Socket™ to PCB

Step 2

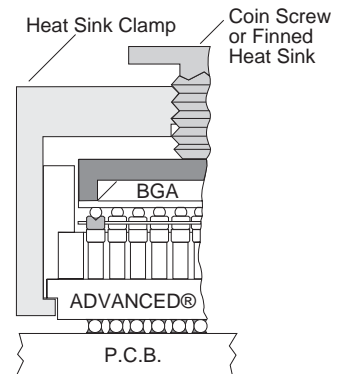
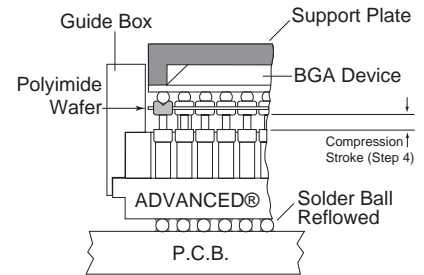
- Align and place BGA device on top of True BGA Socket mating contacts. Place Chip Support Plate over BGA device.

Step 3

- Slide Clamp over assembly. Allow space on PCB for sliding clamp [approximately 33% of device package size on one side only with new Short Slide Clamp]. Refer to Clamp Sliding Directions for pin 1 location (see page 4).

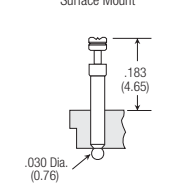
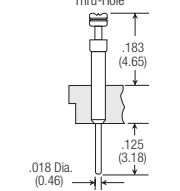
Step 4

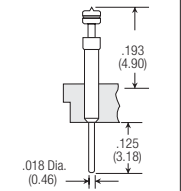
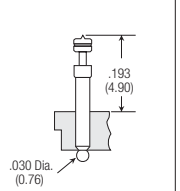
- Tighten Coin Screw or Finned Heat Sink to engage compression stroke.

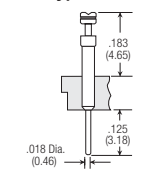
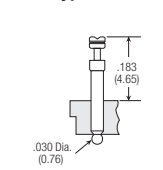
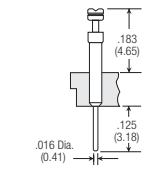


1.27mm Pitch Terminal Options

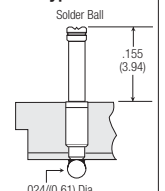
 Standard Terminals
for Production Applications

Type -690
Surface Mount

Type -708
Thru-Hole

 Terminals for LGA or
De-balled BGA Device Applications

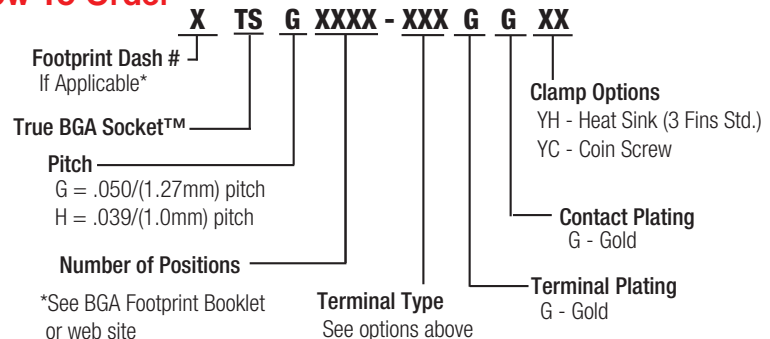
Type -712

Type -713

 Terminals for BGA Device Test Applications
(Consult Factory for Availability)

Type -657

Type -659

Type -709


1.0mm Pitch Terminal

Type -752


How To Order



Mechanical specifications for BGA device package required for quoting/ordering.